

# Yuyang WANG

## CV HIGHLIGHTS

Columbia Nano Initiative, Columbia University

530 West 120th St, New York, NY 10027

+1 (781) 428-0408 @yw3831@columbia.edu wangyy.phd

I design high-bandwidth, energy-efficient, and adaptable connectivity with silicon photonics to transform modern computing systems.

## CURRENT APPOINTMENT

### Columbia University in the City of New York

Postdoctoral Research Scientist, Columbia Nano Initiative

– Mentored by Prof. Keren Bergman

New York, NY, USA

2021–Present

## EDUCATION

### University of California, Santa Barbara

Ph.D. in Electrical and Computer Engineering

– Co-advised by Prof. Kwang-Ting Cheng and Prof. John E. Bowers

Santa Barbara, CA, USA

2021

### Tsinghua University

B.Eng. in Electronic Engineering

Beijing, China

2015

## PROFESSIONAL EXPERIENCE

### Semiconductor Research Corporation (SRC) Research Scholars Program

Research Scholar, Center for Ubiquitous Connectivity (CUBiC) under SRC JUMP 2.0

2023–Present

– Contributed to the writing and visualization of the proposal that led to the award of \$35M JUMP 2.0 grant for the CUBiC Center

### Hong Kong University of Science and Technology

Postgraduate Visiting Intern, Department of Electrical and Computer Engineering

Hong Kong SAR, China

Aug. 2019–Dec. 2019

### Cadence Design Systems, Inc.

Design Engineering Intern - Photonics, Custom IC & PCB Group

San Jose, CA, USA

Jun. 2018–Sep. 2018

### Rice University

Student Intern, Department of Electrical and Computer Engineering

Houston, TX, USA

Jul. 2014–Sep. 2014

## SELECTED PUBLICATIONS

1. **Y. Wang**, Z. Zhang, J. E. Bowers, and K.-T. Cheng, "Silicon photonics optical interconnects for data-centric artificial intelligence applications: A design automation perspective," in *Frontiers of Electronic Design (FED)*, A. Iranmanesh, Ed., in press, Cham: Springer International Publishing.
2. **Y. Wang**, S. Wang, R. Parsons, A. Novick, V. Gopal, K. Jang, A. Rizzo, C.-P. Chiu, K. Hosseini, T. T. Hoang, S. Shumarayev, and K. Bergman, "Silicon photonics chip I/O for ultra high-bandwidth and energy-efficient die-to-die connectivity," in *2024 IEEE Custom Integrated Circuits Conference (CICC)*, invited, under review, IEEE, 2024.
3. **Y. Wang**, S. Wang, R. Parsons, S. Sanyal, A. Novick, A. Rizzo, K. Jang, V. Gopal, K. J. McNulty, B. Y. Kim, Y. Okawachi, C.-P. Chiu, K. Hosseini, T. T. Hoang, S. Shumarayev, M. Lipson, A. Gaeta, and K. Bergman, "Scalable co-packaged dwdm silicon photonics chip i/o driven by microresonator Kerr frequency combs," *Nature Communications Physics*, 2024, invited, in preparation.
4. **Y. Wang**, S. Wang, A. Novick, A. James, R. Parsons, A. Rizzo, and K. Bergman, "Dispersion-Engineered and Fabrication-Robust SOI Waveguides for Ultra-Broadband DWDM," en, in *Optical Fiber Communication Conference (OFC) 2023*, San Diego California: Optica Publishing Group, 2023, Th3A.4. doi:10.1364/OFC.2023.Th3A.4.
5. **Y. Wang** and K.-T. Cheng, "Traffic-Adaptive Power Reconfiguration for Energy-Efficient and Energy-Proportional Optical Interconnects," in *2021 IEEE/ACM International Conference On Computer Aided Design (ICCAD)*, Munich, Germany: IEEE, Nov. 2021, pp. 1–9. doi:10.1109/ICCAD51958.2021.9643475.
6. **Y. Wang**, P. Sun, J. Hulme, M. A. Seyed, M. Fiorentino, R. G. Beausoleil, and K.-T. Cheng, "Energy Efficiency and Yield Optimization for Optical Interconnects via Transceiver Grouping," *Journal of Lightwave Technology*, vol. 39, no. 6, pp. 1567–1578, Mar. 2021. doi:10.1109/JLT.2020.3039489.
7. **Y. Wang**, J. Hulme, P. Sun, M. Jain, M. A. Seyed, M. Fiorentino, R. G. Beausoleil, and K.-T. Cheng, "Characterization and Applications of Spatial Variation Models for Silicon Microring-Based Optical Transceivers," in *2020 57th ACM/IEEE Design Automation Conference (DAC)*, San Francisco, CA, USA: IEEE, Jul. 2020, pp. 1–6. doi:10.1109/DAC18072.2020.9218608.

## RESEARCH INTERESTS

My research centers on enabling the design of system connectivity that is ultra high-bandwidth, energy-efficient, and adaptable in today's data-driven world. Tackling the significant communication bottlenecks found in modern distributed computing infrastructures, exacerbated by data-intensive AI and machine learning workloads, I am committed to designing—as well as democratizing the design process for—scalable architectures that maximize the capabilities of integrated silicon photonics, bridging communication and computation. With a deeper integration of photonics within computing sockets, I envision a paradigm shift in computing architectures that promises unparalleled interconnection bandwidth density, versatility, and functionalities.

## CURRENT APPOINTMENT

### Columbia University in the City of New York

Postdoctoral Research Scientist, Columbia Nano Initiative

New York, NY, USA

2021–Present

- Mentored by Prof. Keren Bergman

## EDUCATION

### University of California, Santa Barbara

Ph.D. in Electrical and Computer Engineering

Santa Barbara, CA, USA

2018–2021

- Co-advised by Prof. Kwang-Ting Cheng and Prof. John E. Bowers

### University of California, Santa Barbara

M.S. in Electrical and Computer Engineering

Santa Barbara, CA, USA

2015–2018

### Tsinghua University

B.Eng. in Electronic Engineering

Beijing, China

2011–2015

## PROFESSIONAL EXPERIENCE

### Semiconductor Research Corporation (SRC) Research Scholars Program

Research Scholar, Center for Ubiquitous Connectivity (CUBIC) under SRC JUMP 2.0

2023–Present

- Contributed to the writing and visualization of the proposal that led to the award of \$35M JUMP 2.0 grant for the CUBIC Center

### Hong Kong University of Science and Technology

Postgraduate Visiting Intern, Department of Electrical and Computer Engineering

Hong Kong SAR, China

Aug. 2019–Dec. 2019

### Cadence Design Systems, Inc.

Design Engineering Intern - Photonics, Custom IC & PCB Group

San Jose, CA, USA

Jun. 2018–Sep. 2018

### Rice University

Student Intern, Department of Electrical and Computer Engineering

Houston, TX, USA

Jul. 2014–Sep. 2014

## PUBLICATIONS

### Refereed Conference Proceedings

- C1 G. Michelogiannakis, Y. Arafa, B. Cook, L. Y. Dai, A.-H. Hameed Badawy, M. Glick, **Y. Wang**, K. Bergman, and J. Shalf, "Efficient Intra-Rack Resource Disaggregation for HPC Using Co-Packaged DWDM Photonics," in *2023 IEEE International Conference on Cluster Computing (CLUSTER)*, Santa Fe, NM, USA: IEEE, Oct. 2023, pp. 158–172. doi:10.1109/CLUSTER52292.2023.00021.
- C2 S. Wang, A. Novick, A. Rizzo, R. Parsons, S. Sanyal, K. J. McNulty, B. Y. Kim, Y. Okawachi, **Y. Wang**, A. Gaeta, M. Lipson, A. Gaeta, M. Lipson, and K. Bergman, "Integrated, Compact, and Tunable Band-Interleaving of a Kerr Comb Source," in *CLEO 2023*, San Jose, CA: Optica Publishing Group, 2023, STh3J.6. doi:10.1364/CLEO\_SI.2023.STh3J.6.

- C3 **Y. Wang**, S. Wang, A. Novick, A. James, R. Parsons, A. Rizzo, and K. Bergman, "Dispersion-Engineered and Fabrication-Robust SOI Waveguides for Ultra-Broadband DWDM," en, in *Optical Fiber Communication Conference (OFC) 2023*, San Diego California: Optica Publishing Group, 2023, Th3A.4. doi [10.1364/OFC.2023.Th3A.4](https://doi.org/10.1364/OFC.2023.Th3A.4).
- C4 A. James, **Y. Wang**, A. Rizzo, and K. Bergman, "Flexible, Process-Aware Compact Model of Effective Index in Silicon Waveguides for Commercial Foundries," in *2022 International Conference on Numerical Simulation of Optoelectronic Devices (NUSOD)*, Turin, Italy: IEEE, Sep. 2022, pp. 173–174. doi [10.1109/NUSOD54938.2022.9894784](https://doi.org/10.1109/NUSOD54938.2022.9894784).
- C5 **Y. Wang** and K.-T. Cheng, "Traffic-Adaptive Power Reconfiguration for Energy-Efficient and Energy-Proportional Optical Interconnects," in *2021 IEEE/ACM International Conference On Computer Aided Design (ICCAD)*, Munich, Germany: IEEE, Nov. 2021, pp. 1–9. doi [10.1109/ICCAD51958.2021.9643475](https://doi.org/10.1109/ICCAD51958.2021.9643475).
- C6 **Y. Wang**, J. Hulme, P. Sun, M. Jain, M. A. Seyedi, M. Fiorentino, R. G. Beausoleil, and K.-T. Cheng, "Characterization and Applications of Spatial Variation Models for Silicon Microring-Based Optical Transceivers," in *2020 57th ACM/IEEE Design Automation Conference (DAC)*, San Francisco, CA, USA: IEEE, Jul. 2020, pp. 1–6. doi [10.1109/DAC18072.2020.9218608](https://doi.org/10.1109/DAC18072.2020.9218608).
- C7 **Y. Wang** and K.-T. Cheng, "Task Mapping-Assisted Laser Power Scaling for Optical Network-on-Chips," in *2019 IEEE/ACM International Conference on Computer-Aided Design (ICCAD)*, Westminster, CO, USA: IEEE, Nov. 2019, pp. 1–6. doi [10.1109/ICCAD45719.2019.8942146](https://doi.org/10.1109/ICCAD45719.2019.8942146).
- C8 **Y. Wang**, M. A. Seyedi, J. Hulme, M. Fiorentino, R. G. Beausoleil, and K.-T. Cheng, "Bidirectional tuning of microring-based silicon photonic transceivers for optimal energy efficiency," in *Proceedings of the 24th Asia and South Pacific Design Automation Conference*, Tokyo Japan: ACM, Jan. 2019, pp. 370–375. doi [10.1145/3287624.3287649](https://doi.org/10.1145/3287624.3287649).
- C9 **Y. Wang**, M. A. Seyedi, R. Wu, J. Hulme, M. Fiorentino, R. G. Beausoleil, and K.-T. Cheng, "Energy-efficient channel alignment of DWDM silicon photonic transceivers," in *2018 Design, Automation & Test in Europe Conference & Exhibition (DATE)*, Dresden, Germany: IEEE, Mar. 2018, pp. 601–604. doi [10.23919/DATE.2018.8342079](https://doi.org/10.23919/DATE.2018.8342079).
- C10 R. Wu, M. A. Seyedi, **Y. Wang**, J. Hulme, M. Fiorentino, R. G. Beausoleil, and K.-T. Cheng, "Pairing of microring-based silicon photonic transceivers for tuning power optimization," in *2018 23rd Asia and South Pacific Design Automation Conference (ASP-DAC)*, Jeju: IEEE, Jan. 2018, pp. 135–140. doi [10.1109/ASPDAC.2018.8297295](https://doi.org/10.1109/ASPDAC.2018.8297295).
- C11 R. Wu, **Y. Wang**, Z. Zhang, C. Zhang, C. L. Schow, J. E. Bowers, and K.-T. Cheng, "Compact modeling and circuit-level simulation of silicon nanophotonic interconnects," in *Design, Automation & Test in Europe Conference & Exhibition (DATE)*, 2017, Lausanne, Switzerland: IEEE, Mar. 2017, pp. 602–605. doi [10.23919/DATE.2017.7927057](https://doi.org/10.23919/DATE.2017.7927057).
- C12 A. Ghofrani, M. A. Lastras-Montano, **Y. Wang**, and K.-T. Cheng, "In-place Repair for Resistive Memories Utilizing Complementary Resistive Switches," in *Proceedings of the 2016 International Symposium on Low Power Electronics and Design*, San Francisco Airport CA USA: ACM, Aug. 2016, pp. 350–355. doi [10.1145/2934583.2934590](https://doi.org/10.1145/2934583.2934590).
- C13 C. Xu, F. X. Lin, **Y. Wang**, and L. Zhong, "Automated OS-level Device Runtime Power Management," in *Proceedings of the Twentieth International Conference on Architectural Support for Programming Languages and Operating Systems*, Istanbul Turkey: ACM, Mar. 2015, pp. 239–252. doi [10.1145/2694344.2694360](https://doi.org/10.1145/2694344.2694360).

## Refereed Journal Articles

- J1 A. James, A. Rizzo, **Y. Wang**, A. Novick, S. Wang, R. Parsons, K. Jang, M. Hattink, and K. Bergman, "Process Variation-Aware Compact Model of Strip Waveguides for Photonic Circuit Simulation," *Journal of Lightwave Technology*, pp. 1–14, 2023. doi [10.1109/JLT.2023.3238847](https://doi.org/10.1109/JLT.2023.3238847).
- J2 A. Novick, A. James, L. Y. Dai, Z. Wu, A. Rizzo, S. Wang, **Y. Wang**, M. Hattink, V. Gopal, K. Jang, R. Parsons, and K. Bergman, "High-bandwidth density silicon photonic resonators for energy-efficient optical interconnects," *Applied Physics Reviews*, vol. 10, no. 4, p. 041306, Nov. 2023. doi [10.1063/5.0160441](https://doi.org/10.1063/5.0160441).
- J3 Z. Wu, L. Y. Dai, **Y. Wang**, S. Wang, and K. Bergman, "Flexible silicon photonic architecture for accelerating distributed deep learning," *Journal of Optical Communications and Networking*, 2023, to appear.
- J4 **Y. Wang**, P. Sun, J. Hulme, M. A. Seyedi, M. Fiorentino, R. G. Beausoleil, and K.-T. Cheng, "Energy Efficiency and Yield Optimization for Optical Interconnects via Transceiver Grouping," *Journal of Lightwave Technology*, vol. 39, no. 6, pp. 1567–1578, Mar. 2021. doi [10.1109/JLT.2020.3039489](https://doi.org/10.1109/JLT.2020.3039489).
- J5 Z. Zhang, R. Wu, **Y. Wang**, C. Zhang, E. J. Stanton, C. L. Schow, K.-T. Cheng, and J. E. Bowers, "Compact Modeling for Silicon Photonic Heterogeneously Integrated Circuits," *Journal of Lightwave Technology*, vol. 35, no. 14, pp. 2973–2980, Jul. 2017. doi [10.1109/JLT.2017.2706721](https://doi.org/10.1109/JLT.2017.2706721).

## Invited Conference Papers

- I1 **Y. Wang**, A. Novick, R. Parsons, S. Wang, K. Jang, A. James, M. Hattink, V. Gopal, A. Rizzo, C.-P. Chiu, K. Hosseini, T. T. Hoang, and K. Bergman, "Scalable architecture for sub-pJ/b multi-Tbps comb-driven DWDM silicon photonic transceiver," in *Next-Generation Optical Communication: Components, Sub-Systems, and Systems XII*, G. Li, K. Nakajima, and A. K. Srivastava, Eds., San Francisco, United States: SPIE, Mar. 2023, p. 55. doi [10.1117/12.2649506](https://doi.org/10.1117/12.2649506).
- I2 **Y. Wang**, L. Shao, M. A. Lastras-Montano, and K.-T. Cheng, "Taming Emerging Devices' Variation and Reliability Challenges with Architectural and System Solutions [Invited]," in *2019 IEEE 32nd International Conference on Microelectronic Test Structures (ICMTS)*, Kita-Kyushu City, Fukuoka, Japan: IEEE, Mar. 2019, pp. 90–95. doi [10.1109/ICMTS.2019.8730924](https://doi.org/10.1109/ICMTS.2019.8730924).

## Book Chapter

- B1 **Y. Wang**, Z. Zhang, J. E. Bowers, and K.-T. Cheng, "Silicon photonics optical interconnects for data-centric artificial intelligence applications: A design automation perspective," in *Frontiers of Electronic Design (FED)*, A. Iranmanesh, Ed., in press, Cham: Springer International Publishing.

## Under Review and In Preparation

- P1 A. Novick, M. Hattink, A. Rizzo, **Y. Wang**, V. Gopal, S. Wang, R. Parsons, and K. Bergman, "Integrated photonic resonant modulator-based equalization and optimization for DWDM," in *Optical Fiber Communication Conference (OFC) 2024*, under review, Optica Publishing Group, 2024.
- P2 S. Wang, **Y. Wang**, X. Meng, K. Hosseini, T. T. Hoang, and K. Bergman, "Automated tuning of ring-assisted MZI-based interleaver for DWDM systems," in *Optical Fiber Communication Conference (OFC) 2024*, under review, Optica Publishing Group, 2024.
- P3 **Y. Wang**, S. Wang, R. Parsons, A. Novick, V. Gopal, K. Jang, A. Rizzo, C.-P. Chiu, K. Hosseini, T. T. Hoang, S. Shumarayev, and K. Bergman, "Silicon photonics chip I/O for ultra high-bandwidth and energy-efficient die-to-die connectivity," in *2024 IEEE Custom Integrated Circuits Conference (CICC)*, invited, under review, IEEE, 2024.
- P4 **Y. Wang**, S. Wang, R. Parsons, S. Sanyal, A. Novick, A. Rizzo, K. Jang, V. Gopal, K. J. McNulty, B. Y. Kim, Y. Okawachi, C.-P. Chiu, K. Hosseini, T. T. Hoang, S. Shumarayev, M. Lipson, A. Gaeta, and K. Bergman, "Scalable co-packaged dwdm silicon photonics chip i/o driven by microresonator Kerr frequency combs," *Nature Communications Physics*, 2024, invited, in preparation.
- P5 Z. Wu, R. Parsons, S. Wang, **Y. Wang**, and K. Bergman, "Wavelength reconfigurable transceiver for multi-interface compute accelerator networks," in *Optical Fiber Communication Conference (OFC) 2024*, under review, Optica Publishing Group, 2024.

## TALKS AND PRESENTATIONS

---

- Invited talk** SPIE Photonics West, San Francisco, CA, USA Jan. 2023  
*Scalable Architecture for Sub-pJ/b Multi-Tbps Comb-Driven DWDM Silicon Photonic Transceiver*
- Poster** Ph.D. Forum, ACM/IEEE Design Automation Conference (DAC), online virtual event Jun. 2020  
*Design and Optimization of Variation-Aware Runtime-Reconfigurable Optical Interconnects*
- Invited talk** Optical/Photonic Interconnects for Computing Systems (OPTICS) workshop, Dresden, Germany Mar. 2018  
*Optimal Pairing and Non-Uniform Channel Alignment of Microring-based Transceivers for Comb Laser-Driven DWDM Silicon Photonics*
- Invited talk** ECE Departmental Seminar, Hong Kong University of Science and Technology, Hong Kong SAR, China Jan. 2018  
*Variation-Aware Modeling and Design of Silicon Photonic Systems*
- Poster** Optical/Photonic Interconnects for Computing Systems (OPTICS) workshop, Lausanne, Switzerland Mar. 2017  
*Variation-Aware Modeling and Design of Nanophotonic Interconnects*

## PROFESSIONAL SERVICE

---

### Journal Reviewer

- Nature Nanotechnology
- IEEE Journal on Selected Areas in Communications
- IEEE Transactions on Computers
- IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems
- IEEE Transactions on Very Large Scale Integration (VLSI) Systems
- IEEE Access

### Conference External Reviewer

- IEEE International Symposium on High-Performance Computer Architecture (HPCA) 2020

### Textbook Translation

- T1 C. Hawkins, J. Segura, and P. Zarkesh-Ha, *CMOS Digital Integrated Circuits: A First Course (Chinese Edition)*, trans. by **Y. Wang** and Y. Yin. China Machine Press, 2016, original work published by the Institution of Engineering and Technology (IET) in 2013.
- T2 S. Kundu and A. Sreedhar, *Nanoscale CMOS VLSI Circuits: Design for Manufacturability (Chinese Edition)*, trans. by **Y. Wang** and W. Xie. China Science Publishing, 2014, original work published by McGraw-Hill Education in 2010.

## TEACHING EXPERIENCE

---

### Columbia University in the City of New York

New York, NY, USA

Guest Lecturer      Spring 2023    ELEN 9403: Seminar in Photonics (Graduate-level)

### University of California, Santa Barbara

Santa Barbara, CA, USA

Teaching Assistant      Winter 2019    ECE 153B: Sensor & Peripheral Interface Design (Undergraduate-level)

## STUDENT MENTORING

---

### Songli Wang

*Ph.D. Student at Columbia University*

Scalable link architectures, automated post-fabrication tuning

Resulting joint publication(s): [P<sub>2</sub>]–[P<sub>4</sub>], [I<sub>1</sub>]

### Zhenguo Wu

*Ph.D. Student at Columbia University*

Reconfigurable architecture for optically connected systems

Resulting joint publication(s): [P<sub>5</sub>], [J<sub>3</sub>]

### Robert Parsons

*Ph.D. Student at Columbia University*

Compact modeling of silicon photonic devices and circuits

Resulting joint publication(s): [P<sub>3</sub>], [I<sub>1</sub>]

### Aneek E. James

*Ph.D. Student at Columbia University, now with Draper Laboratory*

Wafer-scale process variation extraction and characterization

Resulting joint publication(s): [J<sub>1</sub>], [C<sub>4</sub>]

### Kaylx Jang

*Ph.D. Student at Columbia University*

Dispersion-engineered and fabrication-robust (de-)interleavers

Resulting joint publication(s): [C<sub>3</sub>]

### Max Haimowitz

*Ph.D. Student at Columbia University*

Scripted and automated large-scale silicon photonics chip layout

> 80 mm<sup>2</sup>/reticle fully-scripted layout on a 300 mm full-wafer run

## AWARDS AND HONORS

---

**Graduate Fellowship**, Department of Electrical and Computer Engineering, University of California, Santa Barbara, CA, USA      2015

**Outstanding Thesis Award**, Department of Electronic Engineering, Tsinghua University, Beijing, China      2015

**Scholarship for Sports Excellence**, Department of Electronic Engineering, Tsinghua University, Beijing, China      2014

## REFERENCES

---

Ⓐ : from academia;    ⓘ : from industry

### Ⓐ Keren Bergman

*Charles Batchelor Professor of Electrical Engineering*

Columbia University in the City of New York

[bergman@ee.columbia.edu](mailto:bergman@ee.columbia.edu)

### Ⓐ Kwang-Ting Cheng

*Vice-President for Research and Development, Chair Professor*

Hong Kong University of Science and Technology

[timcheng@ust.hk](mailto:timcheng@ust.hk)

### Ⓐ John E. Bowers

*Director of Institute for Energy Efficiency, Distinguished Professor*

University of California, Santa Barbara

[jbowers@ucsb.edu](mailto:jbowers@ucsb.edu)

### ⓘ Raymond G. Beausoleil

*Senior Fellow and Senior Vice President*

Hewlett Packard Enterprise

[ray.beausoleil@hpe.com](mailto:ray.beausoleil@hpe.com)

### Ⓐ Yuan Xie

*Chair Professor*

Hong Kong University of Science and Technology

[yuanxie@ust.hk](mailto:yuanxie@ust.hk)

### ⓘ M. Ashkan Seyedi

*Principal, Silicon Photonics Products*

Nvidia Corporation

[mseyedi@nvidia.com](mailto:mseyedi@nvidia.com)

### ⓘ Kaveh Hosseini

*Technical Lead, Photonics Co-Packaging Architect*

Intel Corporation

[kaveh.hosseini@intel.com](mailto:kaveh.hosseini@intel.com)